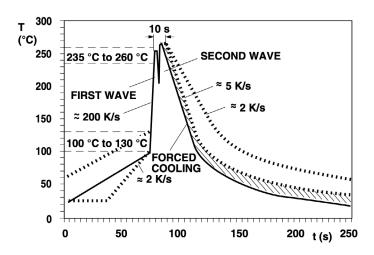
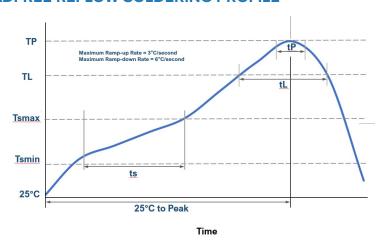


WAVE SOLDERING PROFILE

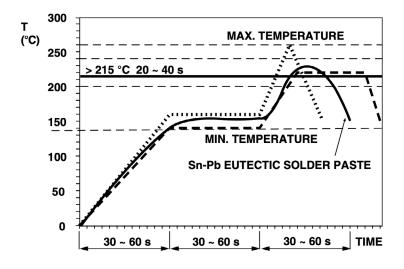


LEADFREE REFLOW SOLDERING PROFILE



PROFILE FEATURE	LEAD FREE
	(SAC 305)
Tsmin	150°C
Tsmax	190°C
Time from Tsmin to Tsmax	60 - 120 seconds
Ramp-up Rate	3°C/second max
Liquidous Temperature	217°C
Time above Liquidous	60 - 120 seconds
Peak Temperature	250°C
Time within 5°C of maximum	10 seconds max
Peak Temperature	
Ramp-down Rate	6°C/second max
Time 25°C to Peak	8min max

SNPB REFLOW SOLDERING PROFILE



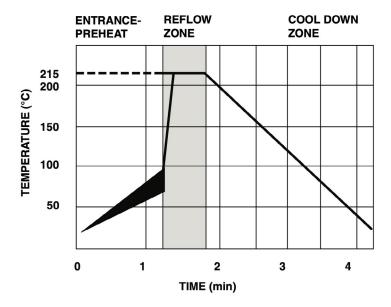
This document is subject to change without notice







VAPOUR PHASE REFLOW PROFILE



HAND SOLDERING

Hand soldering is not recommanded as the thermal shock may cause a crack, hot air pencil use is advised, however if used the following recommendations should be taken:

- Soldering iron tip diameter ≤3.0 mm and wattage max. 20W.
- The Capacitors shall be pre-heated to 150°C and that the temperature gradient between the devices and the tip of the soldering iron.
- Tip temperature ≤280°C and should't be applied for more than 5 seconds.
- The required amount of solder shall be melted on the soldering tip.
- The tip of iron should not contact the ceramic body directly.
- The Capacitors shall be cooled gradually at room temperature after soldering.
- Forced air cooling is not allowed.





